HEAT SINK FOR SEMICONDUCTOR PACKAGE

ABSTRACT OF THE INVENTION

A heat sink (10) for a semiconductor package (38) includes a top surface (12) having a recessed hole (16) at its center. A sidewall (14) formed around the top surface (12) of the heat sink (10) has gaps (18) formed in the sidewall (14). An air vent (22) is formed at a corner of the heat sink (10). The heat sink (10) is used for center gate molding. Mold compound (24) enters the recessed hole (16), covers an IC die 30, and exits via the gaps (18). During mold injection, air escapes through the air vent (22).

[FIG. 1]